

ER 46/17/18 Core

Series/Type: B66377
Date: October 2022

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# **公TDK**

B66377

## ER 46/17/18

### Core

- Round center leg particularly suitable for use of thick winding wires or tapes
- For compact winding design with low leakage inductance
- Delivery mode: single units

#### Magnetic characteristics (per set)

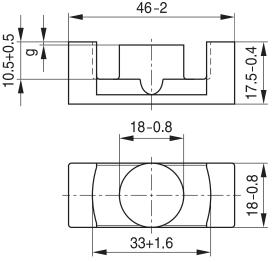
 $\Sigma I/A = 0.34 \text{ mm}^{-1}$ 

- l<sub>e</sub> = 79 mm
- $A_{e} = 233 \text{ mm}^{2}$

 $A_{min} = 226 \text{ mm}^2$ 

 $V_{e} = 18400 \text{ mm}^{3}$ 

Approx. weight 98 g/set



FEK0762-7

## Ungapped

Material	A <sub>L</sub> value nH	μ <sub>e</sub>	P <sub>V</sub> W/set	Ordering code
N27	5700 +30/-20%	1550	< 3.62 (200 mT, 25 kHz, 100 °C)	B66377G0000X127
N87	6100 +30/–20%	1650	< 9.70 (200 mT, 100 kHz, 100 °C)	B66377G0000X187

### **Gapped** (A<sub>L</sub> values/air gaps examples)

Material	g mm	A <sub>L</sub> value approx. nH	μ <sub>e</sub>	Ordering code
N27	1.00 ±0.05	343	93	B66377G1000X127

The  $A_L$  value in the table applies to a core set comprising one ungapped core (dimension g = 0 mm) and one gapped core (dimension g > 0 mm).

Other A<sub>L</sub> values/air gaps and materials available on request – see Processing remarks on page 3.

Calculation factors (for formulas, see "E cores: general information")

Material	Relationship between air gap – A <sub>L</sub> value		Calculation of saturation current				
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N27	343	-0.826	589	-0.847	546	-0.865	

Validity range:

K1, K2: 0.10 mm < s < 1.00 mm K3, K4: 190 nH < A<sub>L</sub> < 1850 nH

Please read Cautions and warnings and Important notes at the end of this document.



#### Cautions and warnings

#### Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

#### Effects of core combination on A<sub>L</sub> value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

#### Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

#### **NiZn-materials**

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

#### **Ferrite Accessories**

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

#### **Processing remarks**

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter *"Processing notes"*, section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.



#### **Cautions and warnings**

#### Display of ordering codes for TDK Electronics products

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## Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm <sup>2</sup>
A <sub>e</sub>	Effective magnetic cross section	mm <sup>2</sup>
AL	Inductance factor; $A_L = L/N^2$	nH
A <sub>L1</sub>	Minimum inductance at defined high saturation ( $\triangleq \mu_a$ )	nH
A <sub>min</sub>	Minimum core cross section	mm <sup>2</sup>
A <sub>N</sub>	Winding cross section	mm <sup>2</sup>
A <sub>R</sub>	Resistance factor; $A_R = R_{Cu}/N^2$	μΩ = 10 <sup>–6</sup> Ω
В	RMS value of magnetic flux density	Vs/m², mT
ΔB	Flux density deviation	Vs/m², mT
Ê	Peak value of magnetic flux density	Vs/m², mT
ΔÂ	Peak value of flux density deviation	Vs/m², mT
B <sub>DC</sub>	DC magnetic flux density	Vs/m², mT
B <sub>R</sub>	Remanent flux density	Vs/m², mT
B <sub>S</sub>	Saturation magnetization	Vs/m², mT
C <sub>0</sub>	Winding capacitance	F = As/V
CDF	Core distortion factor	mm <sup>-4.5</sup>
DF	Relative disaccommodation coefficient DF = $d/\mu_i$	
d	Disaccommodation coefficient	
E <sub>a</sub>	Activation energy	J
f	Frequency	s <sup>−1</sup> , Hz
f <sub>cutoff</sub>	Cut-off frequency	s <sup>−1</sup> , Hz
f <sub>max</sub>	Upper frequency limit	s <sup>−1</sup> , Hz
f <sub>min</sub>	Lower frequency limit	s <sup>−1</sup> , Hz
f <sub>r</sub>	Resonance frequency	s <sup>−1</sup> , Hz
f <sub>Cu</sub>	Copper filling factor	
g	Air gap	mm
Н	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H <sub>DC</sub>	DC field strength	A/m
H <sub>c</sub>	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 <sup>–6</sup> cm/A
h/µ <sub>i</sub> ²	Relative hysteresis coefficient	10 <sup>–6</sup> cm/A
I	RMS value of current	A
I <sub>DC</sub>	Direct current	A
Î	Peak value of current	A
J	Polarization	Vs/m <sup>2</sup>
k	Boltzmann constant	J/K
k <sub>3</sub>	Third harmonic distortion	
k <sub>3c</sub>	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



## Symbols and terms

Symbol	Meaning	Unit
ΔL/L	Relative inductance change	Н
L <sub>0</sub>	Inductance of coil without core	Н
L <sub>H</sub>	Main inductance	Н
Lp	Parallel inductance	Н
L <sub>rev</sub>	Reversible inductance	Н
Ls	Series inductance	Н
l <sub>e</sub>	Effective magnetic path length	mm
I <sub>N</sub>	Average length of turn	mm
Ν	Number of turns	
P <sub>Cu</sub>	Copper (winding) losses	W
P <sub>trans</sub>	Transferrable power	W
P <sub>V</sub>	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = $\omega L/R_s$ = 1/tan $\delta_L$ )	
R	Resistance	Ω
R <sub>Cu</sub>	Copper (winding) resistance (f = 0)	Ω
R <sub>h</sub>	Hysteresis loss resistance of a core	Ω
∆R <sub>h</sub>	R <sub>h</sub> change	Ω
R <sub>i</sub>	Internal resistance	Ω
R <sub>p</sub>	Parallel loss resistance of a core	Ω
R <sub>s</sub>	Series loss resistance of a core	Ω
R <sub>th</sub>	Thermal resistance	K/W
R <sub>V</sub>	Effective loss resistance of a core	Ω
S	Total air gap	mm
Т	Temperature	°C
$\Delta T$	Temperature difference	К
Т <sub>С</sub>	Curie temperature	°C
ť	Time	s
t <sub>v</sub>	Pulse duty factor	
tan δ	Loss factor	
tan δ <sub>l</sub>	Loss factor of coil	
tan δ <sub>r</sub>	(Residual) loss factor at $H \rightarrow 0$	
tan δ <sub>e</sub>	Relative loss factor	
tan δ <sub>h</sub>	Hysteresis loss factor	
tan δ/μ <sub>i</sub>	Relative loss factor of material at $H \rightarrow 0$	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V <sub>e</sub>	Effective magnetic volume	mm <sup>3</sup>
Z	Complex impedance	Ω
Z <sub>n</sub>	Normalized impedance $ Z _n =  Z  / N^2 \times \varepsilon (I_e / A_e)$	Ω/mm

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## Symbols and terms

Symbol	Meaning	Unit	
α	Temperature coefficient (TK)		
$\alpha_{F}$	Relative temperature coefficient of material	1/K	
α <sub>e</sub>	Temperature coefficient of effective permeability	1/K	
ε <sub>r</sub>	Relative permittivity		
Φ	Magnetic flux	Vs	
າ	Efficiency of a transformer		
JB	Hysteresis material constant	mT <sup>-1</sup>	
li	Hysteresis core constant	A-1H-1/2	
s	Magnetostriction at saturation magnetization		
ı	Relative complex permeability		
1 <mark>0</mark>	Magnetic field constant	Vs/Am	
ι <sub>a</sub>	Relative amplitude permeability		
<sup>1</sup> app	Relative apparent permeability		
le	Relative effective permeability		
ι <sub>i</sub>	Relative initial permeability		
ι <sub>p</sub> '	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)		
ι <sub>p</sub> "	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)		
ι <sub>r</sub>	Relative permeability		
<sup>⊥</sup> rev	Relative reversible permeability		
ι <sub>s</sub> '	Relative real (inductive) component of $\overline{\mu}$ (for series components)		
ι <sub>s</sub> "	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)		
<sup>1</sup> tot	Relative total permeability		
	derived from the static magnetization curve		
)	Resistivity	$\Omega m^{-1}$	
EI/A	Magnetic form factor	mm <sup>-1</sup>	
<sup>r</sup> Cu	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	S	
ω	Angular frequency; $\omega = 2 \Pi f$	s <sup>-1</sup>	

All dimensions are given in mm.

Surface-mount device



#### Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (www.tdk-electronics.tdk.com/material). Should you have any more detailed questions, please contact our sales offices.
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- 6. Unless otherwise agreed in individual contracts, **all orders are subject to our General Terms and Conditions of Supply**.

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